

High-Voltage MOSFET

500 V Low- t_{rr} in TO-220 FULLPAK Package



KEY BENEFITS

- Low t_{rr} = 63 ns
 - $R_{DS(on)}$ max: 1.0 Ω at $V_{GS} = 10$ V
 - Industry-best t_{rr} at 63 ns
- Improved EMI results
- Improved efficiency
- Avoids internal body diode recovery failure
- 100 % avalanche tested
- Improved gate charge
- Improved T_{rr} / Q_{rr}

APPLICATIONS

- LLC topology
- Full-bridge topology
- Half-bridge topology
- Double-forward topology

RESOURCES

- Datasheet: SiHF8N50L-E3 - <http://www.vishay.com/doc?91387>
- More featured products: <http://www.vishay.com/ref/featuredmosfets>
- For technical questions contact hvm@vishay.com
- Material categorization: For definitions of compliance please see <http://www.vishay.com/doc?99912>

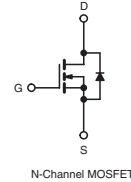
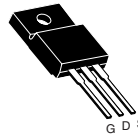


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PRODUCT SUMMARY		
V_{DS} (V) at T_J max.	560	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	1
Q_g (Max.) (nC)	34	
Q_{gs} (nC)	7.8	
Q_{gd} (nC)	10.4	
Configuration	Single	

TO-220 FULLPAK



ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted				
PARAMETER	SYMBOL		LIMIT	UNIT
Drain-Source Voltage	V_{DS}		500	V
Gate-Source Voltage	V_{GS}		± 30	
Continuous Drain Current ^a	V_{GS} at 10 V	$T_C = 25$ °C	I_D	A
Pulsed Drain Current ^b			I_{DM}	
Linear Derating Factor			0.32	W/°C
Single Pulse Avalanche Energy ^c			E_{AS}	mJ
Maximum Power Dissipation	$T_C = 25$ °C		P_D	W
Peak Diode Recovery dV/dt ^d			dV/dt	24 V/ns
Operating Junction and Storage Temperature Range			T_J, T_{stg}	-55 to +150 °C
Soldering Recommendations (Peak Temperature) ^e	for 10 s			300

Notes: a) Drain current limited by maximum junction temperature. b) Repetitive rating; pulse with limited by maximum junction temperature. c) $V_{GS} = 50$ V, starting $T_J = 25$ °C, $L = 10$ mH, $R_g = 25$ Ω , $I_{AS} = 6$ A. d) $I_{SD} \leq 8$ A, $dI/dt \leq 460$ A/ μ s, $V_{GS} \leq V_{DS}$, $T_J \leq 150$ °C. e) 1.6 mm from case.

SPECIFICATIONS $T_J = 25$ °C, unless otherwise noted						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0$ V, $I_D = 250$ μ A	500	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, $I_D = 1$ mA	-	0.5	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250$ μ A	3.0	-	5.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30$ V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500$ V, $V_{GS} = 0$ V	-	-	50	μ A
		$V_{DS} = 400$ V, $V_{GS} = 0$ V, $T_J = 125$ °C	-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10$ V, $I_D = 4.0$ A	-	0.85	1	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50$ V, $I_D = 3$ A	-	2	-	S
Dynamic						
Input Capacitance	C_{iss}	$V_{GS} = 0$ V, $V_{DS} = 25$ V, $f = 1.0$ MHz	-	873	-	pF
Output Capacitance	C_{oss}		-	105	-	
Reverse Transfer Capacitance	C_{rss}		-	11	-	
Total Gate Charge	Q_g	$V_{GS} = 0$ V, $I_D = 6$ A, $V_{DS} = 400$ V	-	22	34	nC
Gate-Source Charge	Q_{gs}		-	7.8	-	
Gate-Drain Charge	Q_{gd}		-	10.4	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 250$ V, $I_D = 6$ A $R_G = 14$ Ω , $V_{GS} = 10$ V	-	17.3	-	ns
Rise Time	t_r		-	35	-	
Turn-Off Delay Time	$t_{d(off)}$		-	23.6	-	
Fall Time	t_f		-	17	-	
Gate Input Resistance	R_g		$f = 1$ MHz, open drain	-	0.7	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode	-	-	8	A
Pulsed Diode Forward Current	I_{SM}		-	-	22	
Body Diode Voltage	V_{SD}	$T_J = 25$ °C, $I_S = 8$ A, $V_{GS} = 0$ V	-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25$ °C, $I_F = I_S$, $dI/dt = 100$ A/ μ s, $V_R = 15$ V	-	63	-	ns
Body Diode Reverse Recovery Charge	Q_{rr}		-	114	-	nC
Body Diode Reverse Recovery Current	I_{RRM}		-	3.3	-	A

Revision 07-Sep-09

MOSFETs - 500 V with Industry-Best t_{rr} of 63 ns